

Amendments to the Claims

Please cancel claims 32 - 36 and add claims 37 - 42, as indicated herein. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

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1. - 22. (Cancelled)

23. (Previously presented) A slider comprising:

a slider bond pad for electrically connecting the slider to a gimbal, the slider bond pad having at least two layers;

a notch located below the slider bond pad and on an edge of the slider, wherein the edge is adjacent the gimbal; and

wherein the notch and the slider bond pad provide compensation for potential misalignment between the slider and the gimbal.

24. (Previously presented) The slider according to claim 23, wherein the notch has a height with respect to the gimbal of about 25 microns.

25. (Previously presented) The slider according to claim 23, wherein the slider bond pad has a thickness of about 15 microns.

26. (Previously presented) The slider according to claim 23, wherein the slider bond pad has a thickness of about 5 microns.

27. (Previously presented) A slider comprising:

a slider body, wherein the slider body comprises a front side;

a slider bond pad extending from the front side for electrically connecting to a flex on suspension bond pad, the slider bond pad having a pad extension adjacent to the front side and a bond pad adjacent the pad extension; and

a notch located along the front side;

wherein the notch and the slider bond pad provide compensation for potential misalignment between the slider and the gimbal.

28. (Previously presented) The slider according to claim 27, wherein the pad extension comprises nickel iron.

29. (Previously presented) The slider according to claim 28, wherein the bond pad comprises gold.

30. (Previously presented) The slider according to claim 29, wherein the slider bond pad has a height with respect to the gimbal of about 25 microns.

31. (Previously presented) The slider according to claim 29, wherein the slider bond pad has a height with respect to the gimbal of about 15 microns.

32. – 36. (Cancelled)

37. (New) A device comprising:

a bond pad for electrically connecting the device to a holding member, the bond pad having at least two layers;

an indentation along an edge of the device, wherein the indentation is proximate the bond pad and is positioned between the bond pad and the holding member; and

wherein the indentation and the bond pad provide compensation for potential misalignment between the bond pad and the holding member.

38. (New) The device according to claim 37, wherein the at least two layers comprises a first layer and a second layer;

the first layer is proximate the device and the second layer is proximate the first layer;
and

the first layer comprises nickel iron.

39. (New) The device according to claim 38, wherein the second layer comprises gold.

40. (New) The device according to 37, wherein the indentation has a height with respect to the holding of about 25 microns.

41. (New) The device according to claim 37, wherein the bond pad has a thickness of about 5 microns.

42. (New) The device according to claim 37, wherein the bond pad has a thickness of about 15 microns.